

SPEC SHEET (FOR REFERENCE)	SHEET No.	Rev.	Page.
	G05090A	1	1 of 1

TYPE:6PC2302N1A * *

CHIP SIZE	0.56 * 0.43mm
WAFER SIZE	6inch
POSSIBLE DIE PER WAFER	64,000pcs

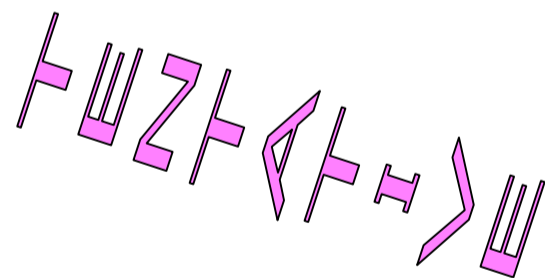
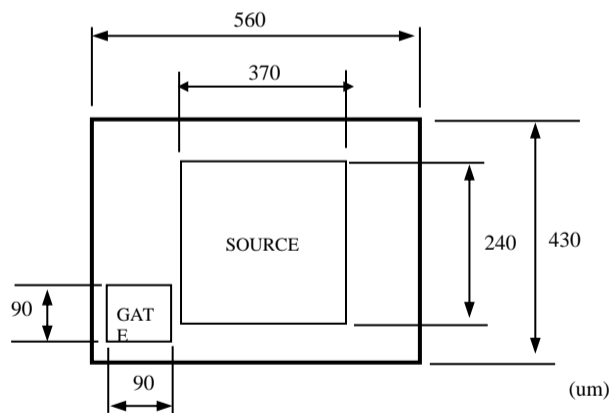
Maximum Ratings(Ta=25°C)

Characteristics	Symbol	Ratings	Unit
Drain-source voltage	VDSS	20	V
Gate-source voltage	VGSS	±8	V

WAFER PROBING SPEC (Ta=25°C)

TEST NO.	MODE	LIMIT				CONDITION
		MIN	Typ	MAX	UNIT	
1	IGSS			±3	uA	VGS=±8.0V VDS=0V
2	IDSS			500	nA	VDS=20.0V VGS=0V
3	BVDSS	23.0			V	ID=250uA
4	VTH	0.53		1.1	V	ID=250uA
5	RDS(on)1		0.14	0.23	ohm	ID=600mA VGS=4.5V
6	RDS(on)2		0.2	0.275	ohm	ID=500mA VGS=2.5V
7	RDS(on)3		0.3	0.7	ohm	ID=350mA VGS=1.8V
8	RDS(on)4		0.5	9.5	ohm	ID=40mA VGS=1.5V
9	VSD	0.5		1.1	V	IS=200mA

※ Built-in ZD between Gate and Source.



NOTE: